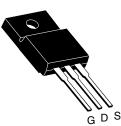
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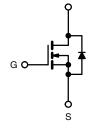


E Series Power MOSFET

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	650)
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.125
Q _g max. (nC)	130)
Q _{gs} (nC)	15	
Q _{gd} (nC)	39	
Configuration	Sing	le

TO-220 FULLPAK





N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
 - LED lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- · Battery chargers
- Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free and Halogen-free	SiHF30N60E-GE3
Lead (Pb)-free	SiHF30N60E-E3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	600	v	
Gate-Source Voltage		V _{GS}	± 30	v	
Continuous Drain Current (T _{.1} = 150 °C) ^d	V_{GS} at 10 V $T_{C} = 25^{\circ}$ $T_{C} = 100^{\circ}$	C L	29		
Continuous Drain Current $(1_j = 150^{\circ} C)^{-1}$	V_{GS} at 10 V $T_C = 100$	°C ^I D	18	А	
Pulsed Drain Current ^a		I _{DM}	76		
Linear Derating Factor			0.29	W/°C	
Single Pulse Avalanche Energy ^b		E _{AS}	690	mJ	
Maximum Power Dissipation		PD	37	W	
Operating Junction and Storage Temperature Range	9	T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	$V_{DS} = 0 V \text{ to } 80 \% V_{DS}$	-1) / / -14	70		
Reverse Diode dV/dt ^e		dV/dt	18	V/ns	
Soldering Recommendations (Peak temperature) ^c	for 10 s		300	°C	
Mounting Torque	M3 screw		0.6	Nm	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 28.2 mH, $R_q = 25 \Omega$, $I_{AS} = 7$ A.

c. 1.6 mm from case.

d. Limited by maximum junction temperature.

e. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

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COMPLIANT HALOGEN

FREE



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PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-		65		00.004		
Maximum Junction-to-Case (Drain)	R _{thJC}	-		3.4		°C/W		
	•							
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	nless otherw	ise noted)						
PARAMETER	SYMBOL		T CONDIT	ONS	MIN.	TYP.	MAX.	UNI
Static		-						•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 2	250 µA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I	_D = 250 μA	-	0.64	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	250 µA	2.0	2.8	4.0	V
Osta Osuma Laskana			$V_{GS} = \pm 20$	V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 1	μA
	1	V _{DS} =	= 600 V, V _G	_S = 0 V	-	-	1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 600 \	/, V _{GS} = 0 V	, V _{GS} = 0 V, T _J = 150 °C		-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	١	₀ = 15 A	-	0.104	0.125	Ω
Forward Transconductance ^a	9 _{fs}	V _D	_S = 8 V, I _D =	= 3 A	-	5.4	-	S
Dynamic						•		•
Input Capacitance	C _{iss}		V _{GS} = 0 V,		-	2600	-	
Output Capacitance	C _{oss}	$V_{DS} = 100 V,$		-	138	-]	
Reverse Transfer Capacitance	C _{rss}		f = 1.0 MHz		-	3	-	1
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	98	-	pF	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$v_{\rm DS} = 0.0$	/ 10 460 V,	V _{GS} = 0 V	-	346	-	
Total Gate Charge	Qg				-	85	130	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	V _{GS} = 10 V I _D = 15 A, V _{DS} = 480 V		-	15	-	nC
Gate-Drain Charge	Q _{gd}				-	39	-	1
Turn-On Delay Time	t _{d(on)}				-	19	40	
Rise Time	t _r	V _{PP} -	V _{DD} = 380 V, I _D = 15 A,		-	32	65	
Turn-Off Delay Time	t _{d(off)}	$V_{\rm GS} = 10 \text{ V}, \text{ R}_{\rm g} = 4.7 \Omega$		-	63	95	ns	
Fall Time	t _f				-	36	75]
Gate Input Resistance	R _g	f = 1	MHz, oper	n drain	-	0.63	-	Ω
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	١ _S	MOSFET sym showing the	MOSFET symbol		-	-	29	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	65	A	
Diode Forward Voltage	V _{SD}	T _J = 25 °(C, I _S = 15 A	, V _{GS} = 0 V	-	-	1.3	V
Body Diode Reverse Recovery Time	t _{rr}		-		-	402	605	ns
Body Diode Reverse Recovery Charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 15 \text{ A},$ dl/dt = 100 A/µs, V _B = 20 V		-	7	15	μC	
		al/at =	TUU A/US \	$I_{D} = 20 V$		1	1	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while $V_{\rm DS}$ is rising from 0 % to 80 % $V_{\rm DSS}.$

b. C_{oss(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}.



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

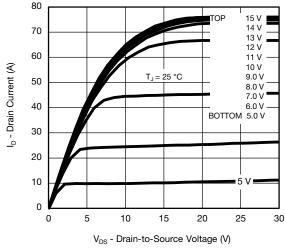
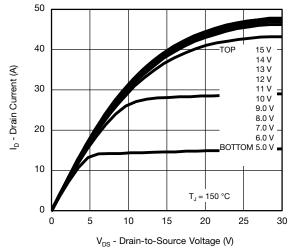
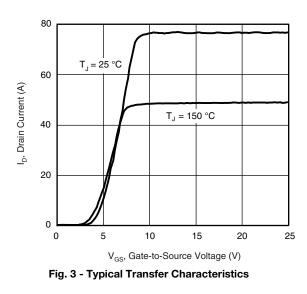


Fig. 1 - Typical Output Characteristics, T_C = 25 °C







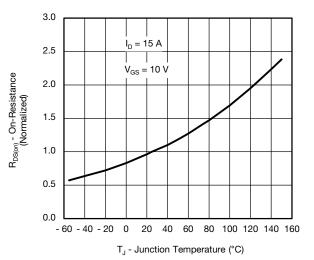


Fig. 4 - Normalized On-Resistance vs. Temperature

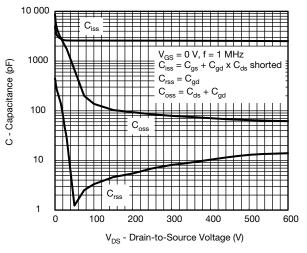
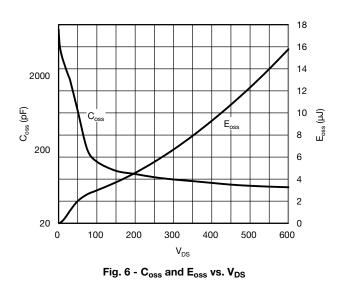


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



3

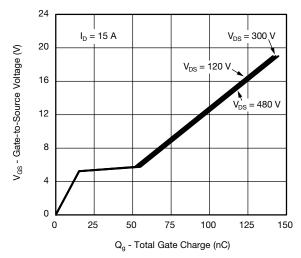
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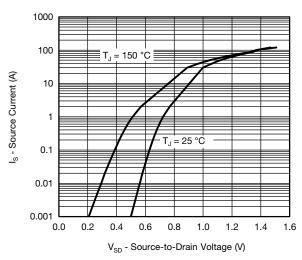
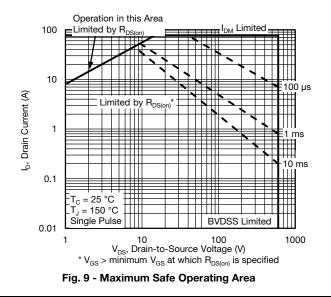


Fig. 8 - Typical Source-Drain Diode Forward Voltage



(25.0) (20.0)(20.

30.0

Fig. 10 - Maximum Drain Current vs. Case Temperature

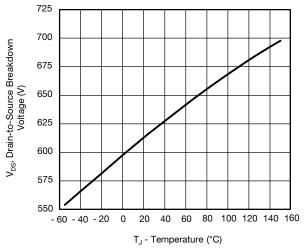


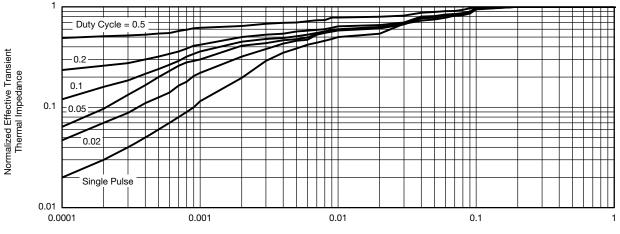
Fig. 11 - Temperature vs. Drain-to-Source Voltage

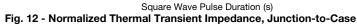
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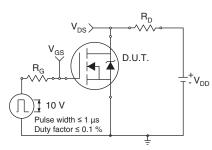


Fig. 13 - Switching Time Test Circuit

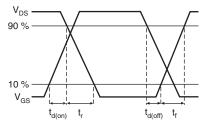


Fig. 14 - Switching Time Waveforms

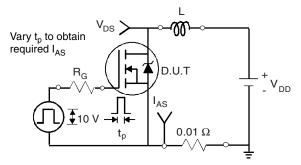


Fig. 15 - Unclamped Inductive Test Circuit

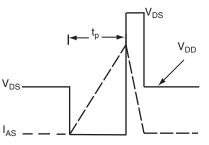


Fig. 16 - Unclamped Inductive Waveforms

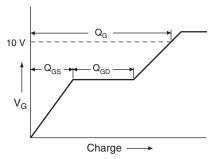
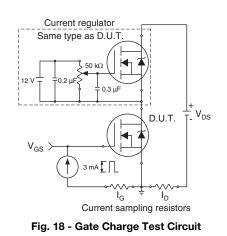


Fig. 17 - Basic Gate Charge Waveform



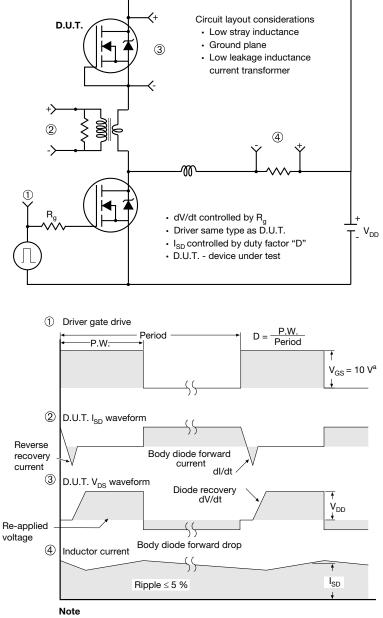
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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5 V$ for logic level devices

Fig. 19 - For N-Channel

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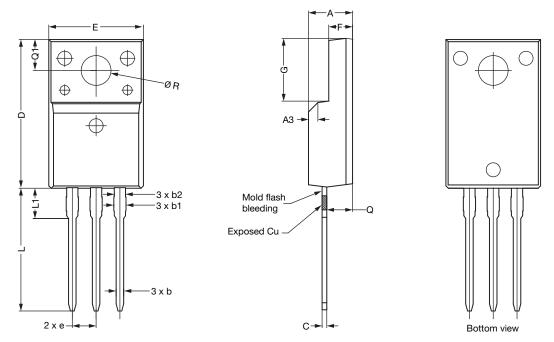
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TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9



		MILLIMETERS	
DIM.	MIN.	NOM.	MAX.
A	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
е		2.54 BSC	
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØR	3.08	3.18	3.28

Notes

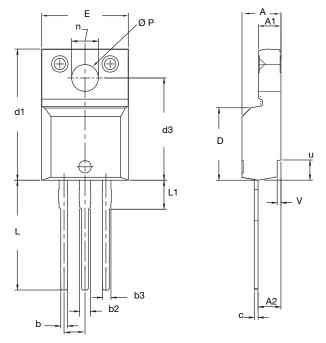
- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking

1



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OPTION 2: FACILITY CODE = Y



	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100) BSC	
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

DWG: 5972

Notes

1. To be used only for process drawing

2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads

3. All critical dimensions should C meet $C_{pk} > 1.33$

4. All dimensions include burrs and plating thickness

5. No chipping or package damage
6. Facility code will be the 1st character located at the 2nd row of the unit marking

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